



Power line chokes

Current-compensated ring core triple chokes
1.3 mH, 520/300 V AC, 20 A, +60 °C

Series/Type: **B82747S4203A020**

Date: May 2015

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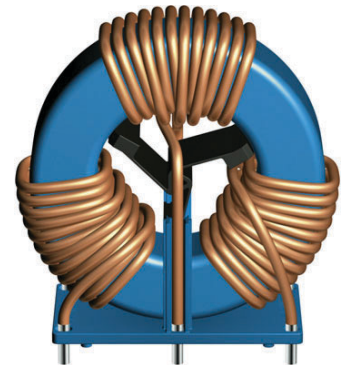
Rated voltage 520 / 300 V AC

Rated inductance 1.3 mH

Rated current 20 A / +60 °C

Construction

- Current-compensated ring core triple choke
- Ferrite core
- Polycarbonate base plate with spacer (UL 94 V-0)
- Sector winding
- Clearance distance ≥ 5.3 mm



Features

- High resonance frequency
- Approx. 1% stray inductance for differential-mode interference suppression
- Suitable for wave soldering
- Design complies with EN 60938-2 (VDE 0565-2)
- RoHS-compatible

Applications

- Suppression of common-mode interferences
- Switch-mode power applications
- Frequency converters

Terminals

- Ends of winding wires
- Hot-dip tinned

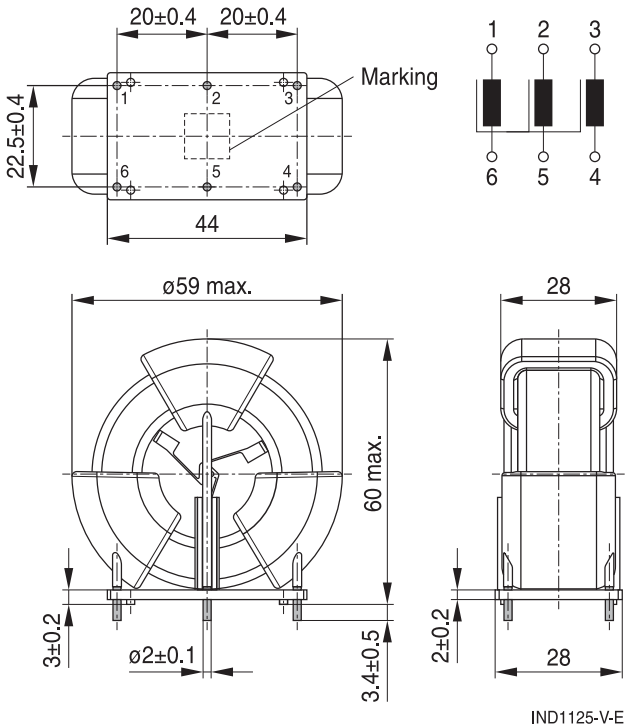
Marking

Product brand, ordering code, rated voltages, rated inductance, rated current, date of manufacture (YYWWD.internal ID code), production place identification code

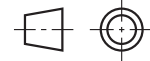
Delivery mode

- Cardboard box

Dimensional drawing and pin configuration



Tolerances to ISO 2768-cl / ISO 8015.
 Size ISO 14405 (E)
 All dimensions in mm

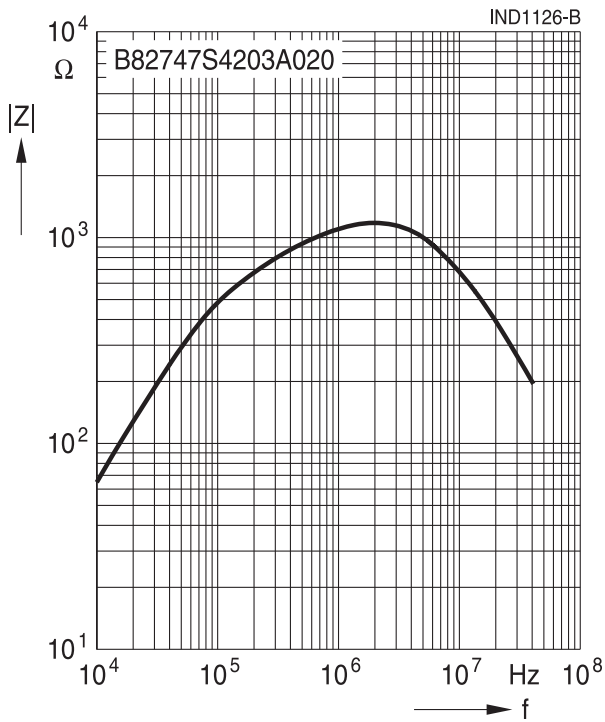


Technical data and measuring conditions

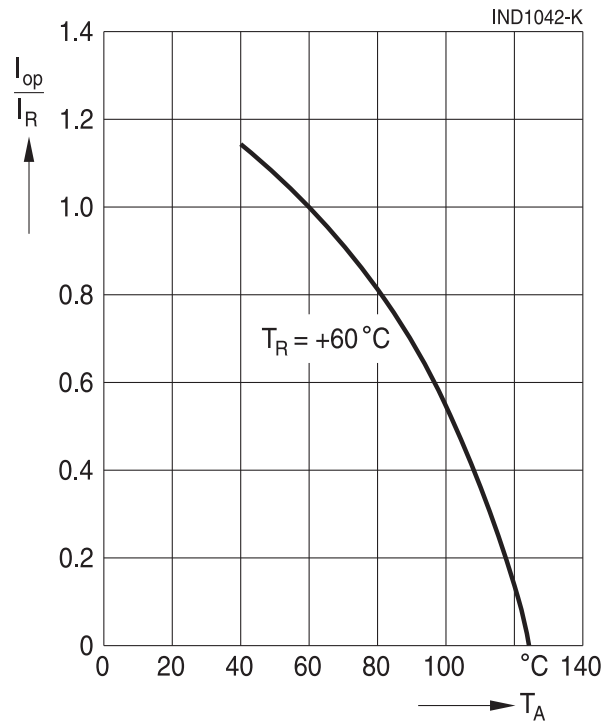
Rated voltage V_R	520/300 V AC (50/60 Hz)
Test voltage V_{test}	2800 V AC, 2 s (line/line)
Rated temperature T_R	+60 °C
Rated current I_R	20 A Referred to rated temperature
Rated inductance L_R	1.3 mH Measured with Agilent 4284A at 10 kHz, 0.1 mA, +20 °C. Inductance is specified per winding.
Inductance tolerance	-30/+50% at +20 °C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with I_R , +20 °C
Stray inductance $L_{stray,typ}$	15 μ H Measured with Agilent 4284A at 10 kHz, 5 mA, +20 °C, typical value
DC resistance R_{max}	5.2 m Ω Measured at +20 °C, maximum value, specified per winding
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: +(245 \pm 5) °C, (3 \pm 0.3) s Wetting of soldering area \geq 95% (to IEC 60068-2-20, test Ta)
Resistance to soldering heat (wave soldering)	+(260 \pm 5) °C, (10 \pm 1) s (to IEC 60068-2-20, test Tb)
Climatic category	40/125/56 (to IEC 60068-1)
Pollution degree	P2 (to IEC 61558-1)
Storage conditions (packaged)	-25 °C ... +40 °C, \leq 75% RH
Weight	Approx. 170 g

Current-compensated ring core triple chokes

Impedance $|Z|$ versus frequency f
 measured with windings in parallel at +20 °C,
 typical value



Current derating I_{op}/I_R
versus ambient temperature T_A
 rated temperature $T_R = +60$ °C



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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Release 2018-10